TELEDYNE e2v
Everywhereyoulook™

ENHANCED EP Flow

Plastic Non-hermetic wired package *

In accordance with Internal procedures

#	Process Flow Steps	Method / Condition	Sampling
1	Plastic Encapsulating Microcircuits (PEM) Assembly	Internal or Subcontractor procedure	100%
2	Incoming inspection	Internal procedure	If appl.
3	Marking	Internal procedure / per Device Specification	100%
4	Temperature Cycling	MIL-STD-883 TM1010 Cond C / +150℃ / -65℃ / 10cy	10 0%
5	Pre-Burn-in electrical	Per Device Specification / +25℃ / +datalog	100%
6	Burn-In	MIL-STD-883 TM1015 / D / 125℃	160Hrs
7	Post-Burn-In (Interim) Electrical	Per Device Specification / +25℃ / +datalog	100%
8	PDA	PDA (amb temp) / +datalog	5%
9	Extreme temp. Electrical	Per Device Specification / +125℃ / -55℃ / +datalog	100%
10	Termination attach	Internal or Subcontractor procedure	If appl.
11	Final Electrical	Per Device Specification / +25℃	If appl.
12	Physical dimension control	Per Device Specification	100%
13	External Visual	MIL-STD-883 TM2009 / Internal procedure	100%
14	Bake	J-STD-033 / 125℃	100%
15	Packing	Internal procedure	100%
16	Certificate of Compliance	MIL-PRF-38535	By delivery

Guaranteed Temperature range	
Enhanced EP	-55℃ < Tc ; Tj < 125℃

*** Quality notes**
Screening for Plastic Encapsulating Microcircuits (PEM) packages
Reliability report upon request

Useful address / Link	
Mil Specs and Drawings	www.landandmaritime.dla.mil
Contact Teledyne-e2v Marketing	semiconductors.MKT@Teledyne-e2v.com
Visit teledyne-e2v website	www.Teledyne-e2v.com